



Material Content Data Sheet



Sales Product Name		IPB090N06N3 G		Issued		4. July 2019		
MA#		MA000398206						
Package		PG-TO263-3-2		Weight*		1557.55 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.120	0.14	0.14	1361	1361
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		59	
	non noble metal	iron	7439-89-6	0.304	0.02		195	
	non noble metal	copper	7440-50-8	304.026	19.52	19.55	195195	195449
	non noble metal	aluminium	7429-90-5	2.792	0.18	0.18	1793	1793
wire	non noble metal	aluminium	7429-90-5	2.792	0.18	0.18	1793	1793
encapsulation	organic material	carbon black	1333-86-4	10.316	0.66		6623	
	plastics	epoxy resin	-	113.481	7.29		72858	
	inorganic material	silicondioxide	60676-86-0	563.965	36.21	44.16	362083	441564
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6200	6200
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	147	148
solder	non noble metal	tin	7440-31-5	0.044	0.00		28	
	noble metal	silver	7440-22-4	0.055	0.00		35	
	non noble metal	lead	7439-92-1	2.095	0.13	0.13	1345	1408
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		106	
	non noble metal	iron	7439-89-6	0.548	0.04		352	
	non noble metal	copper	7440-50-8	547.666	35.16	35.21	351619	352077
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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